

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently amended) An apparatus, ~~having a substrate and an electronic device carried on the substrate~~ comprising:
  - a connecting conductor pattern formed on ~~said~~ a substrate;
  - a device electrode pad formed on ~~said~~ an electronic device; and
  - a plurality of wire thin lines respectively connecting a plurality of portions ~~in~~ on the connecting conductor pattern ~~in said~~ on the substrate and a plurality of portions ~~in said~~ on the device electrode pad ~~in said~~ on the electronic device, wherein ~~said~~ the plurality of wire thin lines differ from one another in mechanical characteristic frequencies in their connected states.
2. (Currently amended) The apparatus according to claim 1, wherein the mechanical characteristic frequency of ~~said~~ one of the plurality of wire thin lines is basically a frequency other than  $n$  ( $n$  is being a natural number) times or  $1/n$  times the mechanical characteristic frequency of the other wire thin lines.
3. (Currently amended) The apparatus according to claim 1, wherein ~~said~~ the plurality of wire thin lines differ from one another in at least one of a length, a line diameter, and material, ~~thereof~~.
4. (Original) The apparatus according to claim 1, which is used as an in-vehicle part.
5. (New) An apparatus comprising:
  - a connecting conductor pattern formed on a substrate;
  - a device electrode pad formed on an electronic device; and

means for connecting a plurality of portions on the connecting conductor pattern on the substrate and a plurality of portions on the device electrode pad on the electronic device, wherein the means for connecting differ in mechanical characteristic frequencies in a connected states.

6 (New) A manufacturing method for a carrying electronic device, comprising:

forming a connecting conductor pattern on a substrate;

forming a device electrode pad on an electronic device;

connecting a plurality of portions on the connecting conductor pattern on the substrate and a plurality of portions on the device electrode pad on the electronic device with a plurality of wire thin lines; and

arranging the plurality of thin lines such that the plurality of thin lines differ from one another in mechanical characteristic frequencies in their connected states.

7. (New) The method according to claim 6, further comprising arranging the plurality of thin lines to differ from one another in at least one of a length, a line diameter and material.

8. (New) The method according to claim 6, further comprising arranging the plurality of thin lines connecting the plurality of portions on the connecting conductor pattern and the plurality of portions on the device electrode pad parallel to each other at positions spaced apart from each other.